

REMARKS

This case has been carefully reviewed and analyzed in view of the Official Action dated November 23, 2005.

The Examiner has rejected claim 12 under 35 U.S.C. 103(a) as being unpatentable over Kuo (U.S. Patent number 6,637,582) in view of Bernreuther et al (U.S. Patent number 5,521,478). Nevertheless, it is respectfully requested that the rejections be withdrawn in light of the following reasons.

The present invention resides in a transporting device for a vertical-type thin circuit board etching machine which utilizes a seamless rail made of anti-corrosive rigid material to guide a lower edge of a circuit board thereby enabling very thin circuit boards to be transmitted smoothly through an etching machine. It is evident that neither Kuo (U.S. Patent number 6,637,582) nor Bernreuther et al (U.S. Patent number 5,521,478) teaches or suggest a seamless rail made of anti-corrosive rigid material to prevent scratching at the edge of the circuit board. The applicant of Kuo (U.S. Patent number 6,637,585) is the son of the applicant of the present application and they are partners of the same company. The Kuo reference (U.S. Patent number 6,637,585) suffers from the drawback that thin circuit boards cannot be transported smoothly and this is the reason why the applicant spent a lot of time, money and efforts to design this invention. The seamless rail made of anti-corrosive rigid material is very important. If the rail is not seamless, then the thin circuit board cannot be transported smoothly. This invention works very well and overcomes the drawbacks suffered from the Kuo reference. As for Bernreuther et al (U.S. Patent number 5,521,478), this reference fails to disclose or teach a seamless rail made of anti-corrosive rigid material to prevent scratching at the edge of the circuit board.

Accordingly, even if the cited references are combined together, the combined disclosure still fails to teach each and every element of the claimed invention and so

the subject matter sought to be patented as a whole would not have been obvious to one of ordinary skill in the art.

It is now believed that the subject Patent Application has been placed in condition of allowance, and such action is respectfully requested.

Respectfully submitted,



Signature

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